

September 1999 Revised October 1999

74LVT374 • 74LVTH374 Low Voltage Octal D-Type Flip-Flop with 3-STATE Outputs

General Description

The LVT374 and LVTH374 are high-speed, low-power octal D-type flip-flops featuring separate D-type inputs for each flip-flop and 3-STATE outputs for bus-oriented applications. A buffered Clock (CP) and Output Enable $(\overline{\rm OE})$ are common to all flip-flops.

The LVTH374 data inputs include bushold, eliminating the need for external pull-up resistors to hold unused inputs.

These octal flip-flops are designed for low-voltage (3.3V) V_{CC} applications, but with the capability to provide a TTL interface to a 5V environment. The LVT374 and LVTH374 are fabricated with an advanced BiCMOS technology to achieve high speed operation similar to 5V ABT while maintaining low power dissipation.

Features

- \blacksquare Input and output interface capability to systems at 5V $\rm V_{CC}$
- Bus-Hold data inputs eliminate the need for external pull-up resistors to hold unused inputs (74LVTH374), also available without bushold feature (74LVT374).
- Live insertion/extraction permitted
- Power Up/Down high impedance provides glitch-free bus loading
- Outputs source/sink -32 mA/+64 mA
- Functionally compatible with the 74 series 374
- Latch-up performance exceeds 500 mA

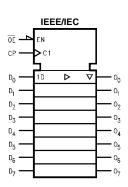
Ordering Code:

	-	
Order Number	Package Number	Package Description
74LVT374WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74LVT374SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LVT374MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74LVTH374WM	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74LVTH374SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74LVTH374MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

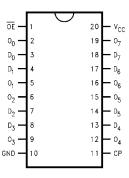
Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

Logic Symbols





Connection Diagram



Pin Descriptions

Pin Names	Description
D ₀ -D ₇	Data Inputs
CP	Clock Pulse Input
ŌĒ	3-STATE Output Enable Input
O ₀ -O ₇	3-STATE Outputs

Truth Table

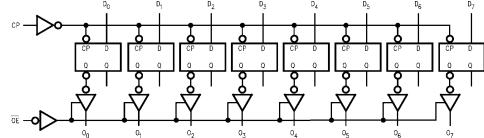
	Outputs		
D _n	СР	ŌĒ	O _n
Н	~	L	Н
L	~	L	L
Х	L	L	O _o
Х	Х	Н	Z

Functional Description

The LVT374 and LVTH374 consist of eight edge-triggered flip-flops with individual D-type inputs and 3-STATE true outputs. The buffered clock and buffered Output Enable are common to all flip-flops. The eight flip-flops will store the state of their individual D inputs that meet the setup and hold time requirements on the LOW-to-HIGH Clock (CP)

transition. With the Output Enable $(\overline{\text{OE}})$ LOW, the contents of the eight flip-flops are available at the outputs. When the $\overline{\text{OE}}$ is HIGH, the outputs go to the high impedance state. Operation of the $\overline{\text{OE}}$ input does not affect the state of the flip-flops.

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

H = HIGH Voltage Level
L = LOW Voltage Level
X = Immaterial
Z = High Impedance

 ^{∠ =} LOW-to-HIGH Transition
 O₀ = Previous O₀ before HIGH-to-LOW of CP

Symbol	Parameter	Value	Conditions	Units
V _{CC}	Supply Voltage	-0.5 to +4.6		V
V _I	DC Input Voltage	-0.5 to +7.0		V
Vo	DC Output Voltage	-0.5 to +7.0	Output in 3-STATE	V
		-0.5 to +7.0	Output in HIGH or LOW State (Note 2)	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
l _{ok}	DC Output Diode Current	-50	V _O < GND	mA
l _o	DC Output Current	64	V _O > V _{CC} Output at HIGH State	mA
		128	V _O > V _{CC} Output at LOW State	IIIA
Icc	DC Supply Current per Supply Pin	±64		mA
I _{GND}	DC Ground Current per Ground Pin	±128		mA
T _{STG}	Storage Temperature	-65 to +150		°C

Recommended Operating Conditions

Symbol	Parameter	Min	Max	Units
V _{CC}	Supply Voltage	2.7	3.6	V
VI	Input Voltage	0	5.5	V
I _{OH}	HIGH-Level Output Current		-32	mA
I _{OL}	LOW-Level Output Current		64	mA
T _A	Free-Air Operating Temperature	-40	85	°C
$\Delta t/\Delta V$	Input Edge Rate, $V_{IN} = 0.8V-2.0V$, $V_{CC} = 3.0V$	0	10	ns/V

Note 1: Absolute Maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum rated conditions is not implied.

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DC Electrical Characteristics $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$ V_{CC}(V) Conditions Symbol Parameter Units Тур Max (Note 3) Input Clamp Diode Voltage 2.7 $I_1 = -18 \text{ mA}$ -1.2 V_{IH} Input HIGH Voltage 2.7-3.6 2.0 V_O ≤ 0.1V or ٧ Input LOW Voltage 2.7-3.6 0.8 $V_O \ge V_{CC} - 0.1V$ V_{OH} Output HIGH Voltage 2.7-3.6 V_{CC} – 0.2 $I_{OH} = -100 \mu A$ $I_{OH} = -8 \text{ mA}$ 2.7 2.4 3.0 2.0 V $I_{OH} = -32 \text{ mA}$ $I_{OL} = 100 \mu A$ Output LOW Voltage V_{OL} 2.7 0.2 ٧ $I_{OL} = 24 \text{ mA}$ 2.7 0.5 V I_{OL} = 16 mA 3.0 0.4 I_{OL} = 32 mA 3.0 0.5 ٧ I_{OL} = 64 mA 3.0 0.55 Bushold Input Minimum Drive I_{I(HOLD)} 3.0 $V_1 = 0.8V$ -75 V_I = 2.0V (Note 4) μΑ $I_{I(OD)}$ Bushold Input Over-Drive 3.0 500 μΑ (Note 5) (Note 4) Current to Change State -500 μΑ (Note 6) Input Current 3.6 10 $V_1 = 5.5V$ Control Pins ±1 $V_I = 0V \text{ or } V_{CC}$ μΑ Data Pins 3.6 -5 μΑ $V_I = 0V$ μΑ $V_I = V_{CC}$ Power Off Leakage Current ±100 $0V \le V_I \text{ or } V_O \le 5.5V$ μΑ I_{OFF} I_{PU/PD} Power up/down 3-STATE $V_0 = 0.5V \text{ to } 3.0V$ μΑ 0-1.5V ±100 Output Current $V_I = GND \text{ or } V_{CC}$ 3-STATE Output Leakage Current 3.6 -5 μΑ $V_0 = 0.5V$ I_{OZL} 3-STATE Output Leakage Current $V_0 = 3.0V$ 3.6 5 μΑ I_{OZH} 3-STATE Output Leakage Current I_{OZH}+ 3.6 10 μΑ $V_{CC} < V_O \le 5.5V$ Power Supply Current 3.6 0.19 Outputs HIGH mΑ I_{CCH} Outputs LOW Power Supply Current I_{CCL} 3.6 5 mΑ Power Supply Current 3.6 0.19 Outputs Disabled mΑ Iccz Power Supply Current I_{CCZ}+ 3.6 0.19 mΑ $V_{CC} \le V_O \le 5.5V$, Outputs Disabled Increase in Power Supply Current One Input at V_{CC} - 0.6V ΔI_{CC} 0.2 3.6 mΑ

Note 3: All typical values are at $V_{CC} = 3.3V$, $T_A = 25^{\circ}C$.

(Note 7)

Note 4: Applies to Bushold versions only (74LVTH374).

Note 5: An external driver must source at least the specified current to switch from LOW-to-HIGH.

Note 6: An external driver must sink at least the specified current to switch from HIGH-to-LOW.

Note 7: This is the increase in supply current for each input that is at the specified voltage level rather than V_{CC} or GND.

Dynamic Switching Characteristics (Note 8)

Symbol	Parameter	V _{CC}	T _A = 25°C			Units	Conditions C _L = 50 pF	
		(,,	Min	Тур	Max		$R_L = 500\Omega$	
V _{OLP}	Quiet Output Maximum Dynamic V _{OL}	3.3		0.8		V	(Note 9)	
V _{OLV}	Quiet Output Minimum Dynamic V _{OL}	3.3		-0.8		V	(Note 9)	

Other Inputs at V_{CC} or GND

Note 8: Characterized in SOIC package. Guaranteed parameter, but not tested.

Note 9: Max number of outputs defined as (n). n-1 data inputs are driven 0V to 3V. Output under test held LOW.

AC Electrical Characteristics

Symbol			$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$ $C_L = 50 \text{ pF, } R_L = 500\Omega$					
	Parameter		$V_{CC} = 3.3V \pm 0.3V$	/	V _{CC} = 2.7V		Units	
		Min	Typ (Note 10)	Max	Min	Max		
f _{MAX}	Maximum Clock Frequency	160			160		MHz	
t _{PHL}	Propagation Delay	1.8		4.9	1.8	5.1	ns	
t _{PLH}	CP to O _n	1.8		4.8	1.8	5.2		
t _{PZL}	Output Enable Time	1.3		5.0	1.3	5.8	no	
t_{PZH}		1.6		4.7	1.6	5.3	ns	
t _{PLZ}	Output Disable Time	1.9		4.6	1.9	4.9	ns	
t_{PHZ}		2.0		4.7	2.0	5.0	115	
t _W	Pulse Width	3.0			3.0		ns	
t _S	Setup Time	1.5			2.0		ns	
t _H	Hold Time	0.8			0.0		ns	

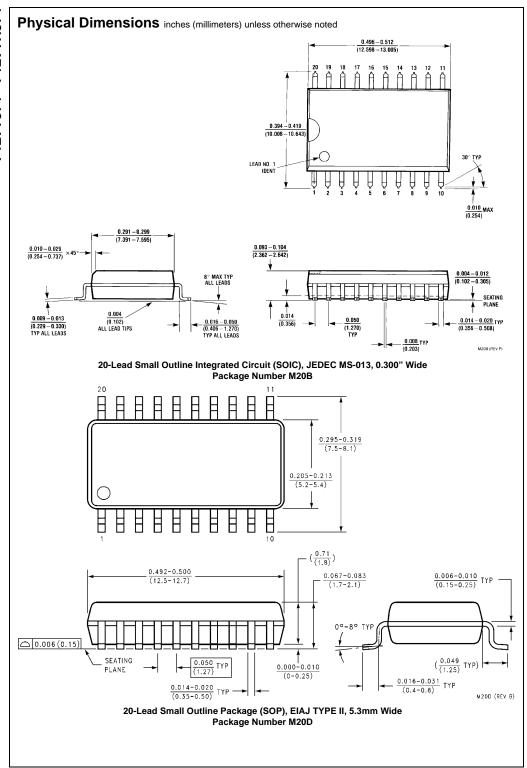
Note 10: All typical values are at $V_{CC}=3.3V,\, T_A=25^{\circ}C.$

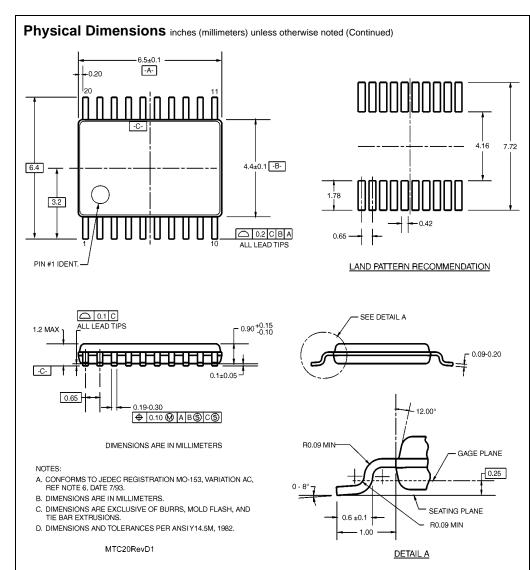
Capacitance (Note 11)

Symbol	Parameter	Conditions	Typical	Units
C _{IN}	Input Capacitance	$V_{CC} = 0V$, $V_I = 0V$ or V_{CC}	3	pF
C _{OUT}	Output Capacitance	$V_{CC} = 3.0V$, $V_O = 0V$ or V_{CC}	5	pF

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Note 11: Capacitance is measured at frequency f = 1 MHz, per MIL-STD-883, Method 3012.





20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC20

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